Index

account management teams 123–4, 126
ACE Logic 76
Acer Group 4, 20, 100, 168, 217, 220–21
manufacturing decision 24, 177–96
research and development strategy 24, 53, 56, 197–216
TSMC-Acer 78, 87
Acer Institute of Education 181
Acer Laboratories Inc. 85
Acer Test 154–5, 164
acquisitions and merger strategy 165–6
‘active provider’ 128–9
Advanced Device Technology Inc. 40
Advanced Micro Devices (AMD) 8, 11, 17, 83, 119, 137
Advanced Microelectronic Products Inc. 15
Advanced Semiconductor Engineering 24
Advanced Semiconductor Manufacturing 103
AdvanTest Inc. 154–5, 163
alliances see strategic alliances
American deposit receipt (ADR) 77
analogical/digital mixed-signal process 79
Anam Semiconductor Inc. (ASI) 168
Annual Customer Relation Survey 126
Application Specific Integrated Circuit (ASIC) 13–14
Applied Materials China (AMC) 138–9
Applied Materials Europe (AME) 117
Applied Materials Japan (AMJ) 117
Applied Materials Korea (AMK) 117
Applied Materials South East Asia (AMSEA) 117
Applied Materials Taiwan (AMT) 18, 23, 113–39, 217
ASE 166, 167–8
ASE TEST 164, 166–7
‘Asian Flu’ (impact) 63–4
Asian Tigers 51, 52
Asian Vegetable Research and Development Centre 63
‘Aspire Park’ 197
assembly plants (Acer) 183–4
Assembly Testing Organisation (ATO) 142, 143, 146–7, 152
asset specificity 105, 110
Asynchronous Transfer Mode (ATM) 60
AT&T Bell 127
ATI Technologies Inc. 96
Austin Volume Manufacturing Centre 116
Bell Laboratories 6, 127
benefit schemes (at AMT) 133–4
Bi Complementary Metal Oxide Semiconductor (BiCMOS) 79
Biomedical Engineering Center 27
biotechnology 55, 56, 57–8
bureaucratic costs 107
business taxes 61
capacity strategy (TSMC) 85, 87–8, 93
capital-intensive industry 161
career planning (in AMT) 132
CCL (Taiwan) 76
CD-ROMs 42–3
Center for Measurement Standards 42
‘central kitchens’ (at Acer) 184–5
centralisation 166, 167, 181–2
Centre of Electronics Industry Development and Research 12
chaebols 3
Chang, Alan 181
Chang, Bonin 120
Chang, Morris 36, 44, 45, 92–3, 120, 136
Chang Chuan Chemical Company 43
Chartered Semiconductor 102, 103, 137
Chiao Tung Bank 69, 154–5
Chiao Tung University 32, 44
China 61, 103, 221–2
Acer in 24, 188–95, 202–3, 206–14
AMT’s future challenges 136–9
China Development Corporation 95
Ching Hwa University 32, 44
chip-makers (AMT) 23, 113–39
ChipMOSE 164, 167
chips 15, 96
Chung-hua Institution for Economic Research 30
Chung Yuan Christian University 134
client relationships (MXIC) 71–3, 74
–server operations (ACER) 186–7
Closer Economic Partnership Agreements (CEPA) 222
clusters/cluster effect 19, 23, 58, 200, 204, 207, 223
cognition discrepancy (UTC) 172
commercial development (Acer) 198, 200
commercial ICs 103
communication challengers 203–5
communications ICs 103–4
Compaq 168, 215
compensation schemes (at AMT) 133–4
competition 46–7, 105–6
AMT 115, 117, 121, 127, 130
global semiconductor industry 221–3
Taiwan foundries 101–2
in testing market 163–4
trends in market (TSMC) 83–5, 86
competitive advantage 2, 14, 17, 20, 223
Acer 187, 216
AMT 115, 117, 121, 127, 134
Philips Taiwan 151
UMC 99, 110, 111
Complementary Metal Oxide Semiconductor (CMOS) 33, 35, 40, 58, 79, 80
Computer and Communications Research Laboratories 27, 32, 42
computers and peripherals 55, 56, 57–8
conflict (ITRI) 46–7
consumer ICs 104
continuous improvement project 128
cooperation 15, 173–4, 204
coordination 109, 173–4
copper process 79, 127
core competencies 17, 18, 23, 71
Acer 186–7, 188
costs
Acer 192–3
labour 64, 65, 192, 216, 221
transport 12, 149
cross-cultural issues (Acer) 203, 212–14
cross-Strait relationships 202–3
CSM 85
culture
cross-cultural issues 203, 212–14
of quality (Philips Taiwan) 151
customer-oriented strategy 94, 122–6, 139
customer satisfaction 93, 123, 126
customers
factory and (relationship) 163–4
response to questions (UTC) 172–3
see also client
customisation (Acer) 185, 200
Da Wang Electrics 14
DAIWA SANKO 74
debt/equity ratio 195
decentralisation 181–2, 187, 206, 221
delivery date, compressed (MXIC) 71
Dell 18, 215
Delta Electronics Inc. 69
demand (AMT’s challenges) 137
demonstration plant set-up plan 33–4
Design Service Alliance 90, 94
Ding-Dang Circle 152
division of labour
global 3, 18, 108, 111
vertical 90, 91, 94
division of work 80–81
Duratek Inc. 138, 139
Dynamic Random Access Memory (DRAM) 6, 14
AMT 118
ITRI 35, 37–40, 46
MXIC 67, 68, 69
TSMC 81–2
UMC 99, 101, 103
UTC 160–62, 164, 169
Index

229
e-foundry model 89–90
economic development (Taiwan) 52, 53
economies of scale 85, 90, 105, 108, 177
Electronic Design Automation vendors 90
Electronic Technical Advisory Committee 12
Electronics Industry Research and Development Centre 27, 33
Electronics Research and Service Organisation 9, 12–15, 27, 46, 58
MXIC and 68–9, 76
phases of 33–40
Electronics Testing Centre 59
Elementary Law for Science and Technology 49
Elitegroup Computer System (ECS) 74
embedded memory process 79
emerging markets, Acer and 188
employees
  Acer 193–4, 202, 212, 214
  AMT 130–36
  professional (spread/influence) 43–5
  specialists 40–44, 45
  turnover 32–3, 171–2
see also labour
employment philosophy (AMT) 131
empowerment (of employees) 212
Energy and Resources Laboratories 27
entrepreneurship 7
  value-chain approach 218, 219, 220–21
entry barriers (UMC) 110–11
environment 134, 135, 161, 208
equipment manufacturer (ATM) 129
equipment providers 113–14
Erasable Programmable Read Only Memory (EPROM) 69, 71, 75
Etron Technology, Inc. 37
excess capacity, burden of 107
Executive Listening Session (ELS) 126
exit barriers 107, 109
expatriate personnel (safety) 193–4
export expansion 51, 52
export processing zones 52, 55, 142, 144
Extended Partition cores 56
fabless model 17, 18, 20, 85, 96, 105–6, 108, 109
fabs 96, 98–101
factory, customer and 163–4
Fairchild Semiconductors 6, 10, 11, 23
‘fast food’ model 184, 187
final testing 156, 158
financial crisis/liabilities (Acer) 195
Fine Products Microelectronics 12
first-mover advantage 111, 129–30, 162–3
First International Computer 164, 166
Flash 68, 69, 71, 75, 160, 161
flexible manufacturing capabilities 94
‘flowing water’ project 121, 135
‘flying geese’ model 52
foreclosure 106
foreign direct investment 50, 221
foreign investment (in Taiwan’s semiconductor industry) 7–8, 10–13
foreign research and development site (key reasons) 208, 209
Formosa Plastics 36, 189
foundry 75
  business model 90–92
  e-foundry 89–90
  international 102–3
  pure-play 95, 99–100, 101, 103–4, 105, 109, 111–12
  pure foundry model 106–8, 111
service (ICs) 79–80, 95, 99–105, 109, 111–12
Fujitsu 11, 60
  functions (local control) 185
Gates, Bill 1
GATT 64
GE 11
GEC Plessey 102
General Instruments 7, 8, 10, 11, 74, 120
global division of labour 3, 18, 108, 111
global information industry 1, 2, 3–4
global inventory management 187
global manufacturing strategy 183–5
global semiconductor industry 221–3
globalisation 117, 207, 223
government
  intervention 2–3, 4–5, 51–3
  involvement (innovation) 51–3
research and development 10, 13–14, 58
roles 58–9, 218–19
Grace 138
Great King 41
‘green hill’ plans 122, 133
H & Q Asian Pacific 69
He Teh Integrated Circuits 15
high-tech development 53–4
high-tech industry (TSMC model) 23, 78–94
Highlight Optoelectronics Inc. 42
Hitachi 11, 161
Ho, Irving 120
Holtek Semiconductor Inc. 15, 38, 40–41
horizontal cooperation/coordination 173–4
horizontal distribution 3
HP 18, 74
Hsinchu Science-based Industrial Park 8, 14, 19, 53–4, 68, 153, 183, 219
AMT 114, 118, 120, 128, 130–31, 136
cluster effect 19, 23, 149
complete service package 60–62
future challenges 63–5
government role 21, 23, 58–9
human resources in 59
impact of ‘Asian Flu’ 63–4
industries in 18, 55–8
ITRI 27, 43–4, 52
research and development 59–60
TSMC 79, 84
UMC 95, 101, 104
Hsuan, John 104
Hsuin, Ming-tze 34
Hu, Ding-Hwa 34, 45, 69
Hualon Microelectronics Corporation 14–15, 38, 40–41
human capital 32, 130–31
human resource management 59
Acer 190–92, 195, 212, 214
AMT 130–33, 136
ITRI 32
Hyundai Electronics Industries 103, 161
IBM 4, 5, 60, 83–4, 102, 120, 137, 164, 169–70, 215, 221
IMEC 222
import duties 61
import substitution 51, 52, 223
IMPS 102
income tax 61
India 222
individual development plan 132
Individual Product Satisfaction Survey 126
industrial development (Taiwan) 10–19
Industrial Development Bureau 77
industrial parks
intelligent 54–5, 219
HSIP see Hsinchu Science-based Industrial Park (HSIP)
TSIP 19, 21, 23, 48, 62–3, 65, 78, 219
Industrial Technology Institute 26
Industrial Technology Research Institute (ITRI) 5, 7, 21, 52, 55, 68, 92, 136, 148, 166
characteristic position 30–33
competition and conflict 46–7
ERSO see Electronics Research and Service Organisation (ERSO)
Institute of Electronics 10
maturity of 217, 219–20
network and supply centre 40–45
organisational change 44, 47–9
status (past and future) 26–30
submicron project 8, 10, 15, 18, 36–40, 46, 118
industries (in HSIP) 18, 55–8
Infineon 73
information industry 1–6, 217–24
infrastructure 2, 21, 52, 65, 193, 220–21
initiative problem (UTC) 174–5
innovation 5, 12, 47–8, 105, 107, 108, 198
inputs (regional sourcing) 189–90
Installed Base Support Survey 126
Institute of Electronics 10
Institute for Information Industry 21
institutes (role/function) 10, 20–23
integrated circuits 7, 68
birth of (ERSO) 33–40
design 5, 12, 15, 16, 81
fabrication (UMC) 23, 95–112
foundry service 79–80, 95, 99–105, 109, 111–12
<table>
<thead>
<tr>
<th>Index</th>
<th>Page</th>
</tr>
</thead>
<tbody>
<tr>
<td>industry 23–4, 55–8, 141–52, 218</td>
<td></td>
</tr>
<tr>
<td>market shares 15, 81, 82</td>
<td></td>
</tr>
<tr>
<td>memory development 156, 160</td>
<td></td>
</tr>
<tr>
<td>packaging 24, 81, 142, 146, 148–9, 153–75</td>
<td></td>
</tr>
<tr>
<td>Philips 24, 141–2, 146, 148–9</td>
<td></td>
</tr>
<tr>
<td>testing 24, 81, 153–75</td>
<td></td>
</tr>
<tr>
<td>integrated device manufacture (IDM) 20, 67–8, 72, 80–81, 83, 85, 89–92, 153–75</td>
<td></td>
</tr>
<tr>
<td>Integrated Solution Provider 72, 77</td>
<td></td>
</tr>
<tr>
<td>Intel 11, 68, 85, 102, 120, 169, 170, 177, 208</td>
<td></td>
</tr>
<tr>
<td>intellectual property 87</td>
<td></td>
</tr>
<tr>
<td>products/services 90</td>
<td></td>
</tr>
<tr>
<td>protection management 212, 213</td>
<td></td>
</tr>
<tr>
<td>protection strategy 205–6, 212</td>
<td></td>
</tr>
<tr>
<td>rights 49, 80, 223</td>
<td></td>
</tr>
<tr>
<td>royalties 73, 75</td>
<td></td>
</tr>
<tr>
<td>‘intelligent’ industrial parks 54–5, 219</td>
<td></td>
</tr>
<tr>
<td>International Material Research Company (IMR) 35</td>
<td></td>
</tr>
<tr>
<td>International Sematech 80</td>
<td></td>
</tr>
<tr>
<td>International Technology Roadmap for Semiconductors (ITRS) 80</td>
<td></td>
</tr>
<tr>
<td>international technology strategy (ACER) 208, 209</td>
<td></td>
</tr>
<tr>
<td>internal problems (of UTC) 171–5</td>
<td></td>
</tr>
<tr>
<td>Inventec 74</td>
<td></td>
</tr>
<tr>
<td>inventory management, global (Acer) 187</td>
<td></td>
</tr>
<tr>
<td>investment</td>
<td></td>
</tr>
<tr>
<td>foreign 7, 8, 10–13</td>
<td></td>
</tr>
<tr>
<td>foreign direct 50, 221</td>
<td></td>
</tr>
<tr>
<td>in HSIP 56, 57–8</td>
<td></td>
</tr>
<tr>
<td>investor rights 61–2</td>
<td></td>
</tr>
<tr>
<td>restrictions (Acer) 188–9, 192</td>
<td></td>
</tr>
<tr>
<td>return on (ROI) 72</td>
<td></td>
</tr>
<tr>
<td>upsurge (in Taiwan) 10, 17–19</td>
<td></td>
</tr>
<tr>
<td>ISE Laboratories 166</td>
<td></td>
</tr>
<tr>
<td>ISO standards 122, 185, 193, 195</td>
<td></td>
</tr>
<tr>
<td>Japan 6, 17–18, 26, 70</td>
<td></td>
</tr>
<tr>
<td>Joint Development Project (JDP) 128</td>
<td></td>
</tr>
<tr>
<td>joint ventures 8, 15, 36, 79</td>
<td></td>
</tr>
<tr>
<td>Acer 182, 186, 201</td>
<td></td>
</tr>
<tr>
<td>UMC 19, 95, 101, 103–5, 110</td>
<td></td>
</tr>
<tr>
<td>UTC 154, 167–9</td>
<td></td>
</tr>
<tr>
<td>just-in-time (JIT) 35, 128</td>
<td></td>
</tr>
<tr>
<td>Kaohsiung 63</td>
<td></td>
</tr>
<tr>
<td>PSK 23–4, 141–52, 217</td>
<td></td>
</tr>
<tr>
<td>Kaohsiung Electronics Company 68</td>
<td></td>
</tr>
<tr>
<td>Key Account approach 72</td>
<td></td>
</tr>
<tr>
<td>Kleisterlee, Gerard 144</td>
<td></td>
</tr>
<tr>
<td>know-how 26, 34–5, 37, 46, 62, 164, 210, 214</td>
<td></td>
</tr>
<tr>
<td>knowledge transfer (Acer) 210, 212–13</td>
<td></td>
</tr>
<tr>
<td>Korea 103</td>
<td></td>
</tr>
<tr>
<td>L &amp; H (Belgium) 76</td>
<td></td>
</tr>
<tr>
<td>labour</td>
<td></td>
</tr>
<tr>
<td>costs 64, 65, 192, 216, 221</td>
<td></td>
</tr>
<tr>
<td>division of 3, 18, 90, 91, 94, 108, 111</td>
<td></td>
</tr>
<tr>
<td>laws (China/Taiwan) 194</td>
<td></td>
</tr>
<tr>
<td>leading capacity 92, 94</td>
<td></td>
</tr>
<tr>
<td>learning-by-doing 111</td>
<td></td>
</tr>
<tr>
<td>Lee, Kuo-Ding 78</td>
<td></td>
</tr>
<tr>
<td>LG 103</td>
<td></td>
</tr>
<tr>
<td>Li, K.T. 13, 42</td>
<td></td>
</tr>
<tr>
<td>Lin, Nai-xin 138</td>
<td></td>
</tr>
<tr>
<td>lines-of-business (Acer) 215</td>
<td></td>
</tr>
<tr>
<td>Liu, Yin-dar 34, 45</td>
<td></td>
</tr>
<tr>
<td>Lo, Y.C. 144, 151</td>
<td></td>
</tr>
<tr>
<td>loans (at HSIP) 62</td>
<td></td>
</tr>
<tr>
<td>local control of functions (Acer) 185</td>
<td></td>
</tr>
<tr>
<td>local image (of AMT) 134</td>
<td></td>
</tr>
<tr>
<td>local support base (AMT) 135–6</td>
<td></td>
</tr>
<tr>
<td>local touch, achieving (Acer) 182</td>
<td></td>
</tr>
<tr>
<td>Logic 75</td>
<td></td>
</tr>
<tr>
<td>logic devices 96</td>
<td></td>
</tr>
<tr>
<td>Logic IC/testing 156</td>
<td></td>
</tr>
<tr>
<td>‘long breath’ (Acer) 188</td>
<td></td>
</tr>
<tr>
<td>Macronix International Company (MXIC) 15, 20–21, 60, 67–77, 120, 217, 220</td>
<td></td>
</tr>
<tr>
<td>Malaysia 103</td>
<td></td>
</tr>
<tr>
<td>management</td>
<td></td>
</tr>
<tr>
<td>Acer 187, 203–5, 208–9, 213, 215</td>
<td></td>
</tr>
<tr>
<td>AMY 121–2</td>
<td></td>
</tr>
<tr>
<td>UTC 172</td>
<td></td>
</tr>
<tr>
<td>manpower/specialists 40–44, 45</td>
<td></td>
</tr>
<tr>
<td>manufacturing</td>
<td></td>
</tr>
<tr>
<td>global strategy (Acer) 183–5</td>
<td></td>
</tr>
<tr>
<td>Taiwan as regional centre 54–5</td>
<td></td>
</tr>
<tr>
<td>manufacturing pioneer, AMT as 128, 129</td>
<td></td>
</tr>
<tr>
<td>Maquiladora 190</td>
<td></td>
</tr>
</tbody>
</table>

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market

drivers (Acer) 207–8

growth (AMT's challenges) 136–7

share 4, 6, 15, 68, 72, 81–2, 87

UTC 166, 170–71

market economy 2, 3

Mask Department (ERSO) 35

mask duplication 35

MASK ROM 68, 69–71, 73, 75, 81–2

mass production 1, 10, 14, 31, 79–80, 87

materials management (Acer) 193

Materials Research Laboratories 42

Matsushita 60, 76

Maydan, Dan 116

MCC 74

Mechanical Industrial Research Laboratories 27, 42

MEGACHIPS 74, 76

memory ICs/testing 103–4, 156, 160

Mercuries and Associates Ltd 69

mergers and acquisitions 165–7

Metal Oxide Semiconductor (MOS) 13

Metal Research Centre 27, 219

Mexico 185, 190, 196

Microchip 167

microelectronic technology 15, 36–40

Micron 161, 169

Microsoft 1, 177, 200, 208, 213

military services 32

Mineral Industrial Centre 27, 219

Ministry of Economic Affairs (MOEA) 27, 30, 33–4, 47, 68, 75, 189, 219

Ministry of Finance 75

Ministry of National Defence 32

MIPS 76

MIT 32

Mitsubishi 11, 74, 76

mobility barriers 17, 109

Morgan, James C. 116, 137, 138

MOSEL 164, 167

Mosel Vitelic 15, 21, 35–6, 60

motivation (working at Acer) 190–91

Motorola 11, 60, 73, 85, 102–3, 167

Motorola-Chungli 166, 168

MSI 39

multimedia ICs 103–4

multimedia information products 148

mutual ‘hold-up’ problem 108–10

mutual research and development for technology (at UTC) 161

NAFTA 185

NANYA 114, 161, 171

NASDAQ 77, 220

National Cheng-Kung University 63, 68, 120, 134, 138

National Chiao-Tung University 134, 161

National Health Research Institutes 30

National Science Council 30, 55, 62, 219

National Semiconductor Corporation 83–4

National Sun Yat-sen University 63

National Taiwan University 32, 134

National Yulin Institute of Technology 63

NAYYA Plastics Corporation 164

NEC 11, 71, 73, 102, 161, 165, 170

network and supply centre (ITRI) 40–45

networks 3–4, 15, 121, 182, 209, 219

Nintendo 70, 73–4

NKK 73, 76

non-return engineering charges 200

non-volatile memory 68, 69, 72

Noyce, Bob 6

Nvidia 87

‘one-window services’ 60

opto-electronics 42, 43, 55, 56, 57–8

order patterns 168

organisational structure Acer 179–81, 198

UTC 156, 160

original equipment manufacturers (OEMs) 12, 17–18, 65, 109, 142

Acer 177, 183, 186, 200, 201, 211

outsourcing 17, 18, 35, 72, 165, 222

Acer 194, 215

TSMC 81, 92

overtime pay (at Acer) 191

packaging 15, 24, 81, 142, 146, 148–9, 153–75

Palm 73

Pan, Wen-yuan 33

Panasonic 74
partners/partnership 13, 168–9
see also joint ventures; strategic alliances
passive component plant 141–2
patents 60, 73, 80, 223
ITRI (numbers) 27, 30
protection (Acer) 205–6
rights (in HSIP) 62
Philips 7, 10, 11, 12, 36, 59, 74, 76, 78, 79, 101, 141
Philips Semiconductors Kaohsiung (PSK) 23–4, 141–52, 217
Philips Taiwan 24, 142, 144, 146–7, 149–51
Phycomp 142
Picvue Electronics Limited 69
planned economy 2–3, 217
political factors (Acer) 194–5, 212
power 137–9, 144–6
Precision 5000 system 116, 127
precision machinery/materials 55, 56
private enterprise (in Taiwan) 10, 14–17
product architecture 71
product development, commercial 198, 200
product differentiation 106
product refurbishment/enhancement 125
product technology administration (at AMT) 123
production 166
development of (at PSK) 146, 147
management (at MXIC) 71
mass 1, 10, 14, 31, 79–80, 87
sites/facilities (Acer) 183–4
professional staff (spread/influence) 43–4, 45
profit 83, 194
ProMOS 60, 164, 167
Proton 15, 40–41
prototypes 203–6
‘pull-push’ strategy 31
‘pure-play’ foundry 95, 99–100, 101, 103–4, 105, 109, 111–12
pure foundry model 106–8, 111
quality
culture of (Philips Taiwan) 151
policy/principles (UTC) 154, 155
testing of 156, 160
TQM (in UTC) 156, 160
quality circles 151–2
Quality Improvement Committees 151–2
Quality Improvement Teams 151–2
RAMBUS 73, 76, 160, 161, 162, 169, 170
RCA 7, 10, 11, 12, 13, 33, 58
recycle time (at UTC) 173
regional business units (RBUs) 186–7
regional sourcing (of inputs) 189–90
research and development 7, 222, 224
Acer Group 24, 181, 185, 197–216
AMT 116, 118–19, 123, 126–30
clusters see clusters/cluster effect
ERSO see Electronics Research and Service Organisation (ERSO)
by government (Taiwan) 10, 13–14, 58
in HSIP 59–60, 62
ITRI 26, 27, 30–32, 46–8
mutual (for technology) 161
PSK 141–2, 144, 149, 151
responsibility, delegation of (Acer) 181
return on investment (ROI) 72
Ricardian rents 111
risk (at TSMC) 83
Rockwell 68
ROM Code 71
Samsung 11, 37, 70–71, 74, 102, 161
Sanders, Jerry 17
Sanyo 76
Schöckley, William 6
Science Parks in Taiwan 23, 50–65, 217
APOC plan 53
Asian Tiger status (stages) 51, 52
challenges 63–5
economic development 50–51
government involvement in world-class innovation centre 51–3
HSIP see Hsinchu Science-based Industrial Park (HSIP)
TSIP 19, 21, 23, 48, 62–3, 65, 78–9, 219
Scientek Corporation 154–5
securities, listing of (MXIC) 75, 77
Securities and Futures Commission 75
self-designed products 34, 38
self-developed technology 73, 75, 76
semiconductor industry (Taiwan)
MXIC 23, 67–77
PSK 146, 148
success (and future trends) 24, 217–24
UMC 95–6, 97–8
UTC 24, 153–75
semiconductor manufacturers and equipment providers (relationship)
113–14
Semiconductor Manufacturing International Corporation (SMIC) 138
service ethic/culture (TSMC) 85, 87–8, 93
Shanghai laboratory (Acer) 214–15
Sharp 60, 71
shift patterns (at Acer) 191
Shih, Chin-tay 34, 47–8
Shih, Stan 179–82, 184, 185–6, 197, 199, 215
Siemens 60, 151, 161
Silicon-Ware 164
Silicon Integrated Systems (SIS) 20, 40
Silicon Valley
   in Taiwan see Hsinchu Science-based Industrial Park (HSIP)
   in USA 6, 14, 17, 51, 53, 68, 201, 202–4, 210
Siliconix 68
Siliconware Precision Industries Company (SPIC) 24
SiliWare 166
Singapore 102, 103
Singapore Technologies 154–5
single chip process 79
small-firm advantages (UMC) 110–11
small and medium-sized enterprises (SMEs) 31, 54, 219
smile curve 23, 24, 183–6, 218, 220–21
Smithsonian Institution 116
software 207
   customisation (Acer) 200
   development (Acer) 215–16
   engineers 201–4, 208–12, 213, 214, 222
   ‘sole-source’ accounts 92, 94
   Solomon Group 154
Somekh, Sass 116
Sony 73, 151
sourcing regionally (Acer) 189–90
spare parts service (at AMT) 125
special economic zones (SEZs) 190
spin-off companies 34–8, 45–6, 58–9
staff see employees; labour
Stanford Research Park 14
Stanford University 32, 68, 92, 120
‘star strategy’ 10
state-owned enterprise (SOE) system 191, 195
Static Random Access Memory (SRAM) 69, 81–2, 118, 160–61, 162, 164
strategic alliances 15
   AMT 135
   TSMC 89
   UTC 154, 164–5, 167–9
strategic approach (at UTC) 161
strategic business units (SBUs) 182, 186–7, 211, 214
strategic orientation (Philips Taiwan) 149–51
strategic planning (at AMT) 121–2
strategic technology alliance (STA) 60
strategy axes (TSMC) 85, 87–8
structural power orientation (PSK) 144–6
Structure–Conduct–Performance model 167
subcontracting 5, 109
Submicron Association 37
Submicron Plan Consulting Committee 36–7
submicron processing technology 10, 36–40, 46
Submicron project 8, 15, 18, 118
SubMicroTechnology 102, 103
SubMicron User Association 37
succession problems (at Acer) 191–2
Sun, Y.S. 27
sunk costs 110
supply chain 135, 186
   global 3, 7, 15, 17, 18, 71
   synergies 106, 201, 203, 210
Syntek Semiconductor 15, 38, 40–41
System-on-a-Chip (SoC) 72, 73
system integration 89–90
MXIC 69, 71–3, 77
Index

235

Systems on Silicon Manufacturing Company (SSMC) 79

Tainan Science-based Industrial Park (TSIP) 19, 21, 23, 48, 62–3, 65, 78–9, 219

Taipei laboratory (Acer) 198, 200–201

Taiwan

China and 50, 136–9, 188–90
economic indicators 50–51
MXIC 23, 67–77
research and development strengths 210
science parks 23, 50–65
UMC 23, 95–112
USA and 12, 50, 53, 136–9
world-class innovation centre 51–3
see also semiconductor industry (Taiwan)
Taiwan Integrated Circuit Company 148
Taiwan Mask Company 13, 35, 38–9, 44, 59
Taiwan Semiconductor Industry Association (TSIA) 60, 168
Taiwan Semiconductor Manufacturing Corporation (TSMC) 8, 14, 21, 23, 36–8, 41, 44, 56, 59–60, 63, 74, 78–94, 111, 220
AMT and 117–18, 120, 123–4
UTC and 161, 165, 168
Taiwan Semiconductor Technology Centre (TSTC) 155
talent development (in AMT) 131–2
tax incentives (in HSIP) 61
Technical Royalty 75
technology
environment 134, 135, 161, 208
-intensive industry 161
international strategy (Acer) 208, 209
microeconomic 15, 36–40
roadmap 80, 156, 159, 163, 168
self-developed 73, 75, 76
stocks 75, 77, 220
Technology Advisory Council 33, 219
technology strategy (TSMC) 85, 87–8, 93
technology transfer 8, 14, 26, 33–5, 68
Acer 204–5, 207, 209

cooperation and 40–43
UTC 167–8, 169–70
telecommunications 55, 56, 57–8
Temasek Holdings 154–5
testing (at UTC) 24, 153–75
Texas Instrument-Acer 15, 123
Texas Instruments 7, 10, 11, 103, 120, 221
TFT-LCD companies 43
Thailand 102, 103
Toshiba 11, 73, 137
total quality management 156, 160
total solution (AMT) 126, 130
Tower (Israel) 102
training (at AMT) 125, 131–2, 134
transaction cost economics (TCE) 109
transistor 96
transport 189, 212
costs 12, 149
Tsai, C.C. 161, 162–5, 167–9, 170
Tsao, Hsin-cheng 34, 45, 46
Tsao, Robert 95, 99–100
Tseng, Fan-Cheng 45, 83
Tu, David 138, 139
turn-around-time (TAT) 71
Turn-key 115, 167, 168

ULSI 39
Uni-industrial Research Centre 27, 219
‘uniload’ plants (Acer) 183–4, 195
Union Chemical Laboratories 27, 42
United Integrated Circuits Corp. 84
United Microelectronics Corp. (UMC) 7, 10, 13–14, 19, 21, 23, 53, 56, 95–112, 161, 217, 220
ITRI and 34–8, 41, 44, 46
TSMC and 84, 85–7, 92
United Nations 189
United Semiconductor Corporation 84
United Silicon Inc. 84
United Test Centre (UTC) 24, 153–75
UOB 154–5
Uruguay Round 64
USA 6–7, 17–18, 102
Acer and 201, 208–10
Taiwan linkages 12, 50, 53, 136–9
see also Silicon Valley
UTEK Semiconductor Corporation 84

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value-chain approach
(entrepreneurship) 218, 219, 220–21
value chains 20–23, 38, 80, 81, 96, 98, 100, 217, 218
Vanguard 15, 37, 39–40, 46, 59–60, 154, 161, 164
Vate 166
vendor contracts 185
vertical disintegration 14, 15, 17, 105–8, 153
vertical division of labour 90, 91, 94
vertical integration 3, 12, 90, 96, 105, 106, 107–8, 165–6
very large scale integration (VLSI)
technology 7–8, 59, 68, 76, 120
ERSO project 13, 14, 35–6, 38–9
VGA 40, 156
VIA Technologies, Inc. 20, 84, 85, 87
video conferencing project (Acer) 203–5
Virtual Silicon Technology (VST) 56
virtual wafer fab services 87–9
volatile memory 69
wafers
fabs and masks 96, 98–9
production 10, 17, 19, 23, 78–82, 113–39
testing 156, 157
WaferTech 79
Wang, Chinjung 120
Wang, David 116, 120, 138, 139
Wang Kung 60, 63, 65
Wellex 102
Wiener, Klaus 8
Winbond 15, 21, 38, 40, 44, 83
Window VGA 156
work in progress 34, 89
World Bank 189
World DVD Forum 43
World Trade Organisation 64, 189, 221–2
Worldwide Semiconductor Manufacturing Corporation (WSMC) 78, 87, 102
Wu, Chiam 117–22, 127–8, 134, 136–8, 139
Wu, Miin 68–72, 75, 77, 118, 120
Xiamen University 120
Xilinx 104–5, 110
Yageo Corporation 142
Yang, Ding-Yuan 44, 45, 83
Zeven, P. 144, 152
Zhongshan (Acer in) 195–6